



Material Content Data Sheet



Sales Product Name		BGA 416 E6327		Issued		29. August 2013		
MA#		MA000787190						
Package		PG-SOT143-4-1		Weight*		11.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.004	0.03		347	
	non noble metal	tin	7440-31-5	0.001	0.01		89	
	inorganic material	silicon	7440-21-3	0.028	0.26	0.30	2568	3004
leadframe	non noble metal	nickel	7440-02-0	1.673	15.11		151134	
	non noble metal	iron	7439-89-6	2.310	20.87	35.98	208709	359843
wire	noble metal	gold	7440-57-5	0.017	0.16	0.16	1571	1571
encapsulation	organic material	carbon black	1333-86-4	0.104	0.94		9418	
	inorganic material	antimonytrioxide	1309-64-4	0.156	1.41		14127	
	plastics	brominated resin	-	0.195	1.77		17658	
	plastics	epoxy resin	-	1.629	14.72		147151	
	inorganic material	silicondioxide	60676-86-0	4.430	40.02	58.86	400252	588606
leadfinish	non noble metal	tin	7440-31-5	0.217	1.96	1.96	19571	19571
plating	noble metal	silver	7440-22-4	0.303	2.74	2.74	27405	27405
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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